

US Patent & Trademark Office

Patent Public Search | Text View

United States Patent Application Publication

20250254970

Kind Code

A1

Publication Date

August 07, 2025

Inventor(s)

Liu; Wei-Min et al.

Semiconductor Device and Method

Abstract

A method includes forming a gate structure over fins protruding from a semiconductor substrate; forming an isolation region surrounding the fins; depositing a spacer layer over the gate structure and over the fins, wherein the spacer layer fills the regions extending between pairs of adjacent fins; performing a first etch on the spacer layer, wherein after performing the first etch, first remaining portions of the spacer layer that are within inner regions extending between pairs of adjacent fins have a first thickness and second remaining portions of the spacer layer that are not within the inner regions have a second thickness less than the first thickness; and forming an epitaxial source/drain region adjacent the gate structure and extending over the fins, wherein portions of the epitaxial source/drain region within the inner regions are separated from the first remaining portions of the spacer layer.

Inventors: Liu; Wei-Min (Hsinchu, TW), Sung; Hsueh-Chang (Zhubei City, TW), Yeo; Yee-Chia (Hsinchu, TW)

Applicant: Taiwan Semiconductor Manufacturing Co., Ltd. (Hsinchu, TW)

Family ID: 75485338

Appl. No.: 19/185439

Filed: April 22, 2025

Related U.S. Application Data

parent US continuation 18358112 20230725 parent-grant-document US 12310091 child US 19185439

parent US continuation 17826563 20220527 parent-grant-document US 11804408 child US 18358112

parent US continuation 16889397 20200601 parent-grant-document US 11348840 child US 17826563

us-provisional-application US 62927864 20191030

Publication Classification

Int. Cl.: **H10D84/01** (20250101); **H10D30/69** (20250101); **H10D62/00** (20250101); **H10D62/10** (20250101); **H10D62/13** (20250101); **H10D62/40** (20250101); **H10D64/01** (20250101); **H10D84/03** (20250101); **H10D84/85** (20250101)

U.S. Cl.:

CPC **H10D84/017** (20250101); **H10D30/797** (20250101); **H10D62/021** (20250101); **H10D62/116** (20250101); **H10D62/151** (20250101); **H10D62/405** (20250101); **H10D64/015** (20250101); **H10D64/017** (20250101); **H10D84/0177** (20250101); **H10D84/0184** (20250101); **H10D84/0186** (20250101); **H10D84/0188** (20250101); **H10D84/0193** (20250101); **H10D84/038** (20250101); **H10D84/853** (20250101);

Background/Summary

[0001] This application is a continuation of U.S. patent application Ser. No. 18/358,112, filed on Jul. 25, 2023, entitled “Semiconductor Device and Method,” which is a continuation of U.S. patent application Ser. No. 17/826,563, filed on May 27, 2022, now U.S. Pat. No. 11,804,408 issued Oct. 31, 2023, entitled “Semiconductor Device and Method,” which is a continuation of U.S. patent application Ser. No. 16/889,397, filed on Jun. 1, 2020, now U.S. Pat. No. 11,348,840 issued May 31, 2022, entitled “Semiconductor Device and Method,” which claims the benefit of U.S. Provisional Application No. 62/927,864, filed on Oct. 30, 2019, entitled “Higher Inner Initial Growth Height Epitaxial Source Drain,” each application is hereby incorporated herein by reference in its entirety.

BACKGROUND

[0002] Semiconductor devices are used in a variety of electronic applications, such as, for example, personal computers, cell phones, digital cameras, and other electronic equipment. Semiconductor devices are typically fabricated by sequentially depositing insulating or dielectric layers, conductive layers, and semiconductor layers of material over a semiconductor substrate, and patterning the various material layers using lithography to form circuit components and elements thereon.

[0003] The semiconductor industry continues to improve the integration density of various electronic components (e.g., transistors, diodes, resistors, capacitors, etc.) by continual reductions in minimum feature size, which allow more components to be integrated into a given area. However, as the minimum features sizes are reduced, additional problems arise that should be addressed.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

[0004] Aspects of the present disclosure are best understood from the following detailed description when read with the accompanying figures. It is noted that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion.

[0005] FIG. 1 illustrates an example of a FinFET in a three-dimensional view, in accordance with some embodiments.

[0006] FIGS. 2, 3, 4, 5, 6, 7, 8A, 8B, 8C, 9A, 9B, 9C, 10A, 10B, 10C, 11A, 11B, 11C, 12, 13A, 13B, 14A, 14B, 15A, 15B, 16A, 16B, 16C, 17A, 17B, 18A, and 18B are cross-sectional views of intermediate stages in the manufacturing of FinFETs, in accordance with some embodiments.

DETAILED DESCRIPTION

[0007] The following disclosure provides many different embodiments, or examples, for implementing different features of the invention. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, merely examples and are not intended to be limiting. For example, the formation of a first feature over or on a second feature in the description that follows may include embodiments in which the first and second features are formed in direct contact, and may also include embodiments in which additional features may be formed between the first and second features, such that the first and second features may not be in direct contact. In addition, the present disclosure may repeat reference numerals and/or letters in the various examples. This repetition is for the purpose of simplicity and clarity and does not in itself dictate a relationship between the various embodiments and/or configurations discussed.

[0008] Further, spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper” and the like, may be used herein for ease of description to describe one element or feature's relationship to another element(s) or feature(s) as illustrated in the figures. The spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. The apparatus may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein may likewise be interpreted accordingly.

[0009] Various embodiments provide processes for forming source/drain regions having reduced volume and reduced cross-sectional area. The source/drain regions may be formed by depositing a spacer material over fins and filling regions between adjacent fins with the spacer material. An etching process is performed to etch the spacer material such that remaining portions of the spacer material between the adjacent fins are higher than remaining portions of the spacer material outside of the adjacent fins. This can cause the epitaxial source/drain regions to grow laterally between the fins from a lowest point that is higher than the lowest point of lateral growth on the outer sidewalls of the fins. Using the techniques described herein, adjacent source/drain regions may be formed that merge at a higher distance above the substrate, which reduces the cross-sectional area of the merged source/drain region. Semiconductor devices manufactured according to embodiments of the present application and including the source/drain regions may experience reduced gate-to-drain capacitance (C_{gd}), reduced RC delay, faster on/off switching, and boosted device speed.

[0010] FIG. 1 illustrates an example of a FinFET in a three-dimensional view, in accordance with some embodiments. The FinFET comprises a fin 52 on a substrate 50 (e.g., a semiconductor substrate). Isolation regions 56 are disposed in the substrate 50, and the fin 52 protrudes above and from between neighboring isolation regions 56. Although the isolation regions 56 are described/illustrated as being separate from the substrate 50, as used herein the term “substrate” may be used to refer to just the semiconductor substrate or a semiconductor substrate inclusive of isolation regions. Additionally, although the fin 52 is illustrated as a single, continuous material as the substrate 50, the fin 52 and/or the substrate 50 may comprise a single material or a plurality of materials. In this context, the fin 52 refers to the portion extending between the neighboring isolation regions 56.

[0011] A gate dielectric layer 92 is along sidewalls and over a top surface of the fin 52, and a gate electrode 94 is over the gate dielectric layer 92. Source/drain regions 82 are disposed in opposite sides of the fin 52 with respect to the gate dielectric layer 92 and gate electrode 94. FIG. 1 further illustrates reference cross-sections that are used in later figures. Cross-section A-A is along a longitudinal axis of the gate electrode 94 and in a direction, for example, perpendicular to the direction of current flow between the source/drain regions 82 of the FinFET. Cross-section B-B is

perpendicular to cross-section A-A and is along a longitudinal axis of the fin **52** and in a direction of, for example, a current flow between the source/drain regions **82** of the FinFET. Cross-section C-C is parallel to cross-section A-A and extends through a source/drain region of the FinFET. Subsequent figures refer to these reference cross-sections for clarity.

[0012] Some embodiments discussed herein are discussed in the context of FinFETs formed using a gate-last process. In other embodiments, a gate-first process may be used. Also, some embodiments contemplate aspects used in planar devices, such as planar FETs.

[0013] FIGS. **2** through **18B** are cross-sectional views of intermediate stages in the manufacturing of FinFETs, in accordance with some embodiments. FIGS. **2** through **7** illustrate reference cross-section A-A illustrated in FIG. **1**, except for multiple fins/FinFETs. FIGS. **8A**, **9A**, **10A**, **11A**, **13A**, **14A**, **15A**, **16A**, **17A**, and **18A** are illustrated along reference cross-section A-A illustrated in FIG. **1**. FIGS. **8B**, **9B**, **10B**, **11B**, **13B**, **14B**, **15B**, **16B**, **16C**, **17B**, and **18B** are illustrated along a similar cross-section B-B illustrated in FIG. **1**. FIGS. **8C**, **9C**, **10C**, **11C**, and **12** are illustrated along reference cross-section C-C illustrated in FIG. **1**.

[0014] In FIG. **2**, a substrate **50** is provided. The substrate **50** may be a semiconductor substrate, such as a bulk semiconductor, a semiconductor-on-insulator (SOI) substrate, or the like, which may be doped (e.g., with a p-type or an n-type dopant) or undoped. The substrate **50** may be a wafer, such as a silicon wafer. Generally, an SOI substrate is a layer of a semiconductor material formed on an insulator layer. The insulator layer may be, for example, a buried oxide (BOX) layer, a silicon oxide layer, or the like. The insulator layer is provided on a substrate, typically a silicon or glass substrate. Other substrates, such as a multi-layered or gradient substrate may also be used. In some embodiments, the semiconductor material of the substrate **50** may include silicon; germanium; a compound semiconductor including silicon carbide, gallium arsenide, gallium phosphide, indium phosphide, indium arsenide, and/or indium antimonide; an alloy semiconductor including silicon-germanium, gallium arsenide phosphide, aluminum indium arsenide, aluminum gallium arsenide, gallium indium arsenide, gallium indium phosphide, and/or gallium indium arsenide phosphide; or combinations thereof.

[0015] The substrate **50** has a region **50N** and a region **50P**. The region **50N** can be for forming n-type devices, such as NMOS transistors, e.g., n-type FinFETs. The region **50P** can be for forming p-type devices, such as PMOS transistors, e.g., p-type FinFETs. The region **50N** may be physically separated from the region **50P** (as illustrated by divider **51**), and any number of device features (e.g., other active devices, doped regions, isolation structures, etc.) may be disposed between the region **50N** and the region **50P**.

[0016] In FIG. **3**, fins **52** are formed in the substrate **50**. The fins **52** are semiconductor strips. In some embodiments, the fins **52** may be formed in the substrate **50** by etching trenches in the substrate **50**. The etching may be any acceptable etch process, such as a reactive ion etch (RIE), neutral beam etch (NBE), the like, or a combination thereof. The etch may be anisotropic. In some embodiments, the fins **52** may be formed such that adjacent fins **52** are separated by a distance **W1** that is between about 10 nm and about 40 nm. In some embodiments, the fins **52** may be formed having a width **W2** that is between about 5 nm and about 30 nm. In some embodiments, the fins **52** may be formed having a pitch **W3** that is between about 15 nm and about 50 nm.

[0017] The fins **52** may be patterned by any suitable method. For example, the fins **52** may be patterned using one or more photolithography processes, including double-patterning or multi-patterning processes. Generally, double-patterning or multi-patterning processes combine photolithography and self-aligned processes, allowing patterns to be created that have, for example, pitches smaller than what is otherwise obtainable using a single, direct photolithography process. For example, in one embodiment, a sacrificial layer is formed over a substrate and patterned using a photolithography process. Spacers are formed alongside the patterned sacrificial layer using a self-aligned process. The sacrificial layer is then removed, and the remaining spacers may then be used to pattern the fins. In some embodiments, the mask (or other layer) may remain on the fins **52**.

[0018] In FIG. 4, an insulation material 54 is formed over the substrate 50 and between neighboring fins 52. The insulation material 54 may be an oxide, such as silicon oxide, a nitride, the like, or a combination thereof, and may be formed by a high density plasma chemical vapor deposition (HDP-CVD), a flowable CVD (FCVD) (e.g., a CVD-based material deposition in a remote plasma system and post curing to make it convert to another material, such as an oxide), the like, or a combination thereof. Other insulation materials formed by any acceptable process may be used. In the illustrated embodiment, the insulation material 54 is silicon oxide formed by a FCVD process. An anneal process may be performed once the insulation material is formed. In an embodiment, the insulation material 54 is formed such that excess insulation material 54 covers the fins 52. Although the insulation material 54 is illustrated as a single layer, some embodiments may utilize multiple layers. For example, in some embodiments a liner (not shown) may first be formed along a surface of the substrate 50 and the fins 52. Thereafter, a fill material, such as those discussed above may be formed over the liner.

[0019] In FIG. 5, a removal process is applied to the insulation material 54 to remove excess insulation material 54 over the fins 52. In some embodiments, a planarization process such as a chemical mechanical polish (CMP), an etch-back process, combinations thereof, or the like may be utilized. The planarization process exposes the fins 52 such that top surfaces of the fins 52 and the insulation material 54 are level after the planarization process is complete. In embodiments in which a mask remains on the fins 52, the planarization process may expose the mask or remove the mask such that top surfaces of the mask or the fins 52, respectively, and the insulation material 54 are level after the planarization process is complete.

[0020] In FIG. 6, the insulation material 54 is recessed to form Shallow Trench Isolation (STI) regions 56. The insulation material 54 is recessed such that upper portions of fins 52 in the region 50N and in the region 50P protrude from between neighboring STI regions 56. Further, the top surfaces of the STI regions 56 may have a flat surface as illustrated, a convex surface, a concave surface (such as dishing), or a combination thereof. The top surfaces of the STI regions 56 may be formed flat, convex, and/or concave by an appropriate etch. The STI regions 56 may be recessed using an acceptable etching process, such as one that is selective to the material of the insulation material 54 (e.g., etches the material of the insulation material 54 at a faster rate than the material of the fins 52). For example, an oxide removal using, for example, dilute hydrofluoric (dHF) acid may be used.

[0021] The process described with respect to FIGS. 2 through 6 is just one example of how the fins 52 may be formed. In some embodiments, the fins may be formed by an epitaxial growth process. For example, a dielectric layer can be formed over a top surface of the substrate 50, and trenches can be etched through the dielectric layer to expose the underlying substrate 50. Homoepitaxial structures can be epitaxially grown in the trenches, and the dielectric layer can be recessed such that the homoepitaxial structures protrude from the dielectric layer to form fins. Additionally, in some embodiments, heteroepitaxial structures can be used for the fins 52. For example, the fins 52 in FIG. 5 can be recessed, and a material different from the fins 52 may be epitaxially grown over the recessed fins 52. In such embodiments, the fins 52 comprise the recessed material as well as the epitaxially grown material disposed over the recessed material. In an even further embodiment, a dielectric layer can be formed over a top surface of the substrate 50, and trenches can be etched through the dielectric layer. Heteroepitaxial structures can then be epitaxially grown in the trenches using a material different from the substrate 50, and the dielectric layer can be recessed such that the heteroepitaxial structures protrude from the dielectric layer to form the fins 52. In some embodiments where homoepitaxial or heteroepitaxial structures are epitaxially grown, the epitaxially grown materials may be in situ doped during growth, which may obviate prior and subsequent implantations although in situ and implantation doping may be used together.

[0022] Still further, it may be advantageous to epitaxially grow a material in region 50N (e.g., an NMOS region) different from the material in region 50P (e.g., a PMOS region). In various

embodiments, upper portions of the fins **52** may be formed from silicon-germanium (Si.sub.xGe.sub.1-x, where x can be in the range of 0 to 1), silicon carbide, pure or substantially pure germanium, a III-V compound semiconductor, a II-VI compound semiconductor, or the like. For example, the available materials for forming III-V compound semiconductor include, but are not limited to, indium arsenide, aluminum arsenide, gallium arsenide, indium phosphide, gallium nitride, indium gallium arsenide, indium aluminum arsenide, gallium antimonide, aluminum antimonide, aluminum phosphide, gallium phosphide, and the like.

[0023] Further in FIG. **6**, appropriate wells (not shown) may be formed in the fins **52** and/or the substrate **50**. In some embodiments, a P well may be formed in the region **50N**, and an N well may be formed in the region **50P**. In some embodiments, a P well or an N well are formed in both the region **50N** and the region **50P**.

[0024] In the embodiments with different well types, the different implant steps for the region **50N** and the region **50P** may be achieved using a photoresist or other masks (not shown). For example, a photoresist may be formed over the fins **52** and the STI regions **56** in the region **50N**. The photoresist is patterned to expose the region **50P** of the substrate **50**, such as a PMOS region. The photoresist can be formed by using a spin-on technique and can be patterned using acceptable photolithography techniques. Once the photoresist is patterned, an n-type impurity implant is performed in the region **50P**, and the photoresist may act as a mask to substantially prevent n-type impurities from being implanted into the region **50N**, such as an NMOS region. The n-type impurities may be phosphorus, arsenic, antimony, or the like implanted in the region to a concentration of equal to or less than 10^{18} cm.⁻³, such as between about 10^{16} cm.⁻³ and about 10^{18} cm.⁻³. After the implant, the photoresist is removed, such as by an acceptable ashing process.

[0025] Following the implanting of the region **50P**, a photoresist is formed over the fins **52** and the STI regions **56** in the region **50P**. The photoresist is patterned to expose the region **50N** of the substrate **50**, such as the NMOS region. The photoresist can be formed by using a spin-on technique and can be patterned using acceptable photolithography techniques. Once the photoresist is patterned, a p-type impurity implant may be performed in the region **50N**, and the photoresist may act as a mask to substantially prevent p-type impurities from being implanted into the region **50P**, such as the PMOS region. The p-type impurities may be boron, boron fluoride, indium, or the like implanted in the region to a concentration of equal to or less than 10^{18} cm.⁻³, such as between about 10^{16} cm.⁻³ and about 10^{18} cm.⁻³. After the implant, the photoresist may be removed, such as by an acceptable ashing process.

[0026] After the implants of the region **50N** and the region **50P**, an anneal may be performed to repair implant damage and to activate the p-type and/or n-type impurities that were implanted. In some embodiments, the grown materials of epitaxial fins may be in situ doped during growth, which may obviate the implantations, although in situ and implantation doping may be used together.

[0027] In FIG. **7**, a dummy dielectric layer **60** is formed on the fins **52**. The dummy dielectric layer **60** may be, for example, silicon oxide, silicon nitride, a combination thereof, or the like, and may be deposited or thermally grown according to acceptable techniques. A dummy gate layer **62** is formed over the dummy dielectric layer **60**, and a mask layer **64** is formed over the dummy gate layer **62**. The dummy gate layer **62** may be deposited over the dummy dielectric layer **60** and then planarized, such as by a CMP. The mask layer **64** may be deposited over the dummy gate layer **62**. The dummy gate layer **62** may be a conductive or non-conductive material and may be selected from a group including amorphous silicon, polycrystalline-silicon (polysilicon), poly-crystalline silicon-germanium (poly-SiGe), metallic nitrides, metallic silicides, metallic oxides, and metals. The dummy gate layer **62** may be deposited by physical vapor deposition (PVD), CVD, sputter deposition, or other techniques known and used in the art for depositing the selected material. The dummy gate layer **62** may be made of other materials that have a high etching selectivity from the

etching of isolation regions. The mask layer **64** may include, for example, silicon nitride, silicon oxynitride, or the like. In this example, a single dummy gate layer **62** and a single mask layer **64** are formed across the region **50N** and the region **50P**. It is noted that the dummy dielectric layer **60** is shown covering only the fins **52** for illustrative purposes only. In some embodiments, the dummy dielectric layer **60** may be deposited such that the dummy dielectric layer **60** covers the STI regions **56**, extending between the dummy gate layer **62** and the STI regions **56**.

[0028] FIGS. **8A** through **18B** illustrate various additional steps in the manufacturing of embodiment devices. FIGS. **8A** through **18B** illustrate features in either of the region **50N** and the region **50P**. For example, the structures illustrated in FIGS. **8A** through **18B** may be applicable to both the region **50N** and the region **50P**. Differences (if any) in the structures of the region **50N** and the region **50P** are described in the text accompanying each figure. FIGS. **8A**, **9A**, **10A**, **11A**, **13A**, **14A**, **15A**, **16A**, **17A**, and **18A** are illustrated along reference cross-section A-A illustrated in FIG. **1**. FIGS. **8B**, **9B**, **10B**, **11B**, **13B**, **14B**, **15B**, **16B**, **17B**, and **18B** are illustrated along reference cross-section B-B illustrated in FIG. **1**. FIGS. **8C**, **9C**, **10C**, **11C**, and **12** are illustrated along reference cross-section C-C illustrated in FIG. **1**. For clarity, some dimensions or proportions of the features shown in the FIGS. **8C** through **12** may be different than as shown in other Figures.

[0029] In FIGS. **8A**, **8B**, and **8C**, the mask layer **64** (see FIG. **7**) may be patterned using acceptable photolithography and etching techniques to form masks **74**. The pattern of the masks **74** then may be transferred to the dummy gate layer **62**. In some embodiments (not illustrated), the pattern of the masks **74** may also be transferred to the dummy dielectric layer **60** by an acceptable etching technique to form dummy gates **72**. The dummy gates **72** cover respective channel regions **58** of the fins **52**. The pattern of the masks **74** may be used to physically separate each of the dummy gates **72** from adjacent dummy gates. The dummy gates **72** may also have a lengthwise direction substantially perpendicular to the lengthwise direction of respective epitaxial fins **52**.

[0030] Further in FIGS. **8A-8C**, first spacer material **78** is formed on exposed surfaces of the dummy gates **72**, the masks **74**, and/or the fins **52**. The first spacer material **78** is used to form first spacers **80** (see FIGS. **10B-C**). In some embodiments, the first spacer material **78** may be a material such as oxide, a nitride, a material such as silicon oxynitride, silicon oxycarbonitride, silicon oxycarbide, the like, or a combination thereof. In some embodiments, the first spacer material **78** may be formed using a process such as thermal oxidation, CVD, PE-CVD, ALD, PVD, sputtering, or the like. In FIG. **8B**, the first spacer material **78** is shown as extending vertically over the dummy gate **72** and mask **74** and laterally over the fin **52**. In some embodiments, the first spacer material **78** may include multiple layers of one or more materials. In some embodiments, the first spacer material **78** may be formed having a thickness between about 2 nm and about 6 nm.

[0031] After the formation of the first spacer material **78**, implants for lightly doped source/drain (LDD) regions (not explicitly illustrated) may be performed. In the embodiments with different device types, similar to the implants discussed above in FIG. **6**, a mask, such as a photoresist, may be formed over the region **50N**, while exposing the region **50P**, and appropriate type (e.g., p-type) impurities may be implanted into the exposed fins **52** in the region **50P**. The mask may then be removed. Subsequently, a mask, such as a photoresist, may be formed over the region **50P** while exposing the region **50N**, and appropriate type impurities (e.g., n-type) may be implanted into the exposed fins **52** in the region **50N**. The mask may then be removed. The n-type impurities may be the any of the n-type impurities previously discussed, and the p-type impurities may be the any of the p-type impurities previously discussed. The lightly doped source/drain regions may have a concentration of impurities of from about 10^{15} cm.⁻³ to about 10^{19} cm.⁻³. An anneal may be used to repair implant damage and to activate the implanted impurities.

[0032] In FIGS. **9A**, **9B**, and **9C**, second spacer material **79** is formed on the first spacer material **78**. The second spacer material **79** is used to form second spacers **86** (see FIGS. **10B-C**). In some embodiments, the second spacer material **79** may be a material such as an oxide, a nitride, a material such as silicon oxynitride, silicon oxycarbonitride, silicon oxycarbide, the like, or a combination

thereof. The second spacer material **79** may be deposited conformally using a process such as CVD, PE-CVD, ALD, PVD, sputtering, or the like. In some embodiments, the second spacer material **79** may include multiple layers of one or more materials.

[0033] In some embodiments, the second spacer material **79** is formed over the fins **52** such that regions between adjacent fins **52** (e.g., “inner” regions **100A**) are at least partially filled with the second spacer material **79**. The inner regions **100A** may be completely filled with the second spacer material **79**, as shown in FIG. **9C**. As such, the second spacer material **79** may be deposited to a thickness **T1** that is about equal to half of the separation distance **W1'** between the first spacer material **78** on adjacent fins **52** or that is greater than half of the separation distance **W1'**. In other embodiments, the second spacer material **79** may be deposited to a thickness **T1** on the fins **52** that is less than half of the separation distance **W1'**. In some embodiments, the second spacer material **79** may be formed having a deposition thickness **T1** between about 3 nm and about 20 nm. In some cases, the second spacer material **79** filling the inner regions may have a seam.

[0034] The top surface of the second spacer material **79** between the fins **52** may be flat, convex, or concave, which may depend on the separation distance **W1'** and/or the deposition thickness **T1** of the deposited second spacer material **79**. For example, a larger fin separation distance **W1'** or a smaller deposition thickness **T1** may reduce the height **H1** of the second spacer material **79** within the fins **52**. The height **H1** may be greater than the deposition thickness **T1**. A height **H1** of the second spacer material **79** between the fins **52** may be greater than, about the same, or less than the height **H0** of the fins **52** protruding above the STI regions **56**. The height **H1** of the second spacer material **79** between the fins **52** may be between about 3 nm and about 60 nm. By controlling the deposition thickness **T1** and/or the height **H1** of the second spacer material **79**, the minimum inner height **IH** and the height difference **DH** of the epitaxial source/drain regions **82** (see FIG. **11C**) may be controlled.

[0035] Turning to FIGS. **10A**, **10B**, and **10C**, recesses **84** are formed in the fins **52**, in accordance with some embodiments. In FIG. **10C**, the location of the channel regions **58** of the fins **52** under the dummy gate structure (e.g., the channel regions **58** that are not etched to form the recesses **84**) are shown for reference. The recesses **84** may be formed using an etching process **85**, which also etches the first spacer material **78** to form the first spacers **80** and etches the second spacer material **79** to form second spacers **86**. The first spacers **80** and the second spacers **86** may collectively be referred to herein as “gate spacers.” The first spacers **80** and the second spacers **86**, dummy gates **72**, and masks **74** may be collectively referred to herein the “dummy gate structures.” In some embodiments, the etching process **85** includes one or more etching steps, such as one or more anisotropic dry etching steps. In other embodiments, the etching process **85** includes a first etching process that etches the first spacer material **78** and the second spacer material **79** and a second etching process that forms the recesses **84**. The example etching of the first spacer material **78**, second spacer material **79**, and recesses **84** shown in FIGS. **10B-C** is intended to be illustrative, and the etching process **85** may etch the first spacer material **78**, second spacer material **79**, or recesses **84** differently in other embodiments. For example, surfaces of the gate spacers are shown as flat in FIG. **10C**, but may be convex or concave in other embodiments.

[0036] In some embodiments, the etching process **85** may etch portions of the first spacer material **78** or second spacer material **79** different amounts such that different regions of the gate spacers (e.g., of the first spacers **80** and/or second spacers **86**) extend higher above the STI regions **56** than other regions of the gate spacers. For example, after the etching process **85**, regions of the gate spacers extending between adjacent fins **52** may have a greater height above the STI regions **56** than regions that are not between adjacent fins **52**. This is shown in FIG. **10C**, in which the “inner regions” **100A** of the gate spacers (e.g., regions between fins **52**) have a height **H2** adjacent the fins **52**, and “outer regions” **100B** of the gate spacers (e.g., regions not between fins **52**) have a height **H3** adjacent the fins **52** that is less than the height **H2**. In some cases, portions of the gate spacers that are farther from the fins **52** may have a height **H3'** that is less than the height **H3**. In this

manner, the gate spacers have a greater vertical thickness (e.g., the vertical distance between a bottom surface and a top surface of the gate spacers) within the inner regions **100A** than within the outer regions **100B**. In some embodiments, the height **H2** above the STI regions **56** of the gate spacers in the inner regions **100A** may be between about 5 nm and about 40 nm, and the height **H3** (or **H3'**) above the STI regions **56** of the gate spacers in the outer regions **100B** may be between about 0 nm and about 30 nm. The height difference **H4** between heights **H2** and **H3** may be between about 0 nm and about 40 nm. The height **H3** may be greater than, less than, or about the same as the height **H0'** of the etched fins **52** protruding from the STI regions **56**, and the height **H2** may be greater than or about the same as the height **H0'**.

[0037] The height **H2** of the inner regions **100A** of the gate spacers may be larger than the height **H3** of the outer regions **100B** of the gate spacers due to the second spacer material **79** filling (or partially filling) the inner regions **100A** between adjacent fins **52**, as shown in FIG. **9C**. The second spacer material **79** deposited within the inner regions **100A** has exposed top surfaces, and the outer sidewalls of the fins **52** has both exposed top surfaces and exposed side surfaces. Thus, the etching process **85** etches the first spacer material **78** and the second spacer material **79** in the outer regions **100B** at a greater overall rate than the inner regions **100A**. This can result the inner regions **100A** having more remaining gate spacer material after the etching process than the outer regions **100B**. Additionally, the confining presence of the adjacent fins **52** can reduce etchant mobility in the inner regions **100A**, further reducing the etching rate of the inner regions **100A**.

[0038] In this manner, the height **H2**, the height **H3**, and/or the height difference **H4** of the gate spacers may be controlled by controlling the geometry or topology of the structure, such as by controlling the separation distance **W1'** between adjacent fins **52**, the thickness of the first spacer material **78** or the second spacer material **79**, the height **H1** of the second spacer material **79** in the inner regions **100A**, or the like. The heights may also be controlled by controlling the process parameters of the etching process **85**. The process parameters may include, for example, a process gas mixture, a voltage bias, an RF power, a process temperature, a process pressure, other parameters, or a combination thereof. In some embodiments, the shape, volume, area, size, merge height, or other characteristics of the epitaxial source/drain regions **82** (see FIGS. **11B-C**) formed in the recesses **84** may be controlled by controlling the etching process **85** in this manner.

[0039] FIGS. **11A**, **11B**, and **11C** illustrate forming epitaxial source/drain regions **82** in the fins **52**, in accordance with some embodiments. For clarity, some dimensions or proportions of the features shown in the FIGS. **11A-C** may be different than as shown in other Figures. The epitaxial source/drain regions **82** in the region **50N**, e.g., the NMOS region, may be formed by masking the region **50P**, e.g., the PMOS region, and etching source/drain regions of the fins **52** in the region **50N** to form recesses **84** in the fins **52**. Then, the epitaxial source/drain regions **82** in the region **50N** are epitaxially grown in the recesses **84** from exposed portions of the fins **52**. The epitaxial source/drain regions **82** in the region **50P**, e.g., the PMOS region, may be formed by masking the region **50N**, e.g., the NMOS region, and etching source/drain regions of the fins **52** in the region **50P** to form recesses **84** in the fins **52**. Then, the epitaxial source/drain regions **82** in the region **50P** are epitaxially grown in the recesses **84** from exposed portions of the fins **52**. The epitaxial source/drain regions **82** may be epitaxially grown using a suitable process such as CVD, metal-organic CVD (MOCVD), molecular beam epitaxy (MBE), liquid phase epitaxy (LPE), vapor phase epitaxy (VPE), selective epitaxial growth (SEG), the like, or a combination thereof.

[0040] The epitaxial source/drain regions **82** may include any acceptable material, such as appropriate for n-type FinFETs or p-type FinFETs. For example, if the fin **52** is silicon, the epitaxial source/drain regions **82** in the region **50N** may include materials exerting a tensile strain in the channel region **58**, such as silicon, silicon carbide, phosphorous doped silicon carbide, silicon phosphide, or the like. If the fin **52** is silicon, the epitaxial source/drain regions **82** in the region **50P** may comprise materials exerting a compressive strain in the channel region **58**, such as silicon-germanium, boron doped silicon-germanium, germanium, germanium tin, or the like.

[0041] The epitaxial source/drain regions **82** may have surfaces raised from respective surfaces of the fins **52** and may have facets. For example, the surfaces of the epitaxial source/drain regions **82** may have facets having a (111) crystalline orientation, facets of other crystalline orientations, or combinations of differently oriented facets. As illustrated in FIG. **11C**, the epitaxial material formed in the adjacent fins **52** may expand laterally outward beyond sidewalls of the fins **52** along crystalline planes and merge in the inner regions **100A** to form a continuous epitaxial source/drain region **82** extending over multiple adjacent fins **52**. For example, the epitaxial material grown from adjacent fins **52** may merge in the inner regions **100A** at a merge height MH above the STI regions **56**. In this manner, the epitaxial source/drain regions **82** may have a bottom inner surface **83A** extending between adjacent fins **52** within the inner regions **100A** and a bottom outer surface **83B** extending from the fins **52** into the outer regions **100B**. In some cases, the surfaces **83A** and **83B** may be faceted, such as having {111} facets or other facets.

[0042] In some embodiments, lateral growth of the epitaxial material is blocked by the material of the gate spacers. For example, lateral growth in the inner regions **100A** may be blocked below the height H2 of the gate spacers in the inner regions **100A**, and lateral growth in the outer regions **100B** may be blocked below the height H3 of the gate spacers in the outer regions **100B**. In this manner, the bottom inner surface **83A** of the epitaxial source/drain regions **82** extending into the inner regions **100A** may have a minimum inner height IH above the STI regions **56** that is about the same as the height H2 of the gate spacers in the inner regions **100A**. Additionally, the bottom outer surface **83B** of the epitaxial source/drain regions **82** extending into the outer regions **100B** may have a minimum outer height OH above the STI regions **56** that is about the same as the height H3 of the gate spacers in the outer regions **100B**. Due to the height difference H4 of the gate spacers described above, the height IH may be greater than the height OH. In some embodiments, the minimum inner height IH may be between about 5 nm and about 40 nm, and the minimum outer height OH may be between about 0 nm and about 30 nm. The height difference DH between heights IH and OH may be between about 5 nm and about 40 nm.

[0043] In some embodiments, the merge height MH of the epitaxial source/drain region **82** may be controlled by controlling the minimum inner height IH of the epitaxial source/drain region **82**, which may be controlled by controlling the height H2 of the gate spacers in the inner regions **100A**. The height H2 of the gate spacers may be controlled as described previously. In some embodiments, the merge height MH may be between about 5 nm and about 70 nm. The merge height MH may be controlled to be above, below, or about level with the lateral height LH of the epitaxial source/drain regions **82**, which designates the height above the STI regions **56** of the portion of the epitaxial source/drain regions **82** that laterally extends farthest into an outer region **100B**. In some embodiments, the lateral height LH may be between about 30 nm and about 50 nm. In some embodiments, the merge height MH may be controlled to be above, below, or about level with the mid-height (e.g., the height at half the full vertical thickness) of the epitaxial source/drain region **82**, which in some cases may be about the same as the lateral height LH.

[0044] By controlling the merge height MH, the cross-sectional area of the epitaxial source/drain regions **82** may be controlled. For example, a greater MH can correspond to a smaller cross-sectional area of the epitaxial source/drain regions **82**. Additionally, the cross-sectional area of the epitaxial source/drain regions **82** may be controlled by controlling the height difference DH. For example, a greater DH can correspond to a smaller cross-sectional area of the epitaxial source/drain regions **82**. By reducing the cross-sectional area of the epitaxial source/drain regions **82**, the parasitic gate-to-drain capacitance (Cgd) of a FinFET device may be reduced, which can improve performance of the FinFET device. For example, RC delay of the FinFET device may be reduced and the response speed of the FinFET device may be improved. In this manner, increasing the height difference DH can reduce the parasitic capacitance Cgd. In some embodiments, the cross-sectional area of an epitaxial source/drain region **82** with a nonzero DH may be reduced to between about 0% and about 28% of the cross-sectional area of a reference epitaxial source/drain region in

which DH=0.

[0045] In some embodiments, an epitaxial source/drain region **82** may be formed from merged epitaxial material grown in more than two fins **52**. An example multi-fin embodiment is shown in FIG. **12**, though an epitaxial source/drain region **82** may be formed over more or fewer fins **52** than shown. As shown in FIG. **12**, the region between each pair of adjacent fins **52** is an “inner” region. The techniques described herein may be used to reduce the cross-sectional area of the epitaxial source/drain regions **82** in this and other multi-fin embodiments.

[0046] The epitaxial source/drain regions **82** and/or the fins **52** may be implanted with dopants to form source/drain regions, similar to the process previously discussed for forming lightly-doped source/drain regions, followed by an anneal. The source/drain regions may have an impurity concentration of between about 10^{19} cm.⁻³ and about 10^{21} cm.⁻³. The n-type and/or p-type impurities for source/drain regions may be any of the impurities previously discussed. In some embodiments, the epitaxial source/drain regions **82** may be in situ doped during growth. In some embodiments, a profile of the epitaxial source/drain regions **82** is a prism array facing the substrate **50**, which may include shorter prisms sandwiched between higher prisms.

[0047] In FIGS. **13A** and **13B**, a first interlayer dielectric (ILD) **88** is deposited over the structure. The first ILD **88** may be formed of a dielectric material, and may be deposited by any suitable method, such as CVD, plasma-enhanced CVD (PECVD), or FCVD. Dielectric materials may include phospho-silicate glass (PSG), boro-silicate glass (BSG), boron-doped phospho-silicate glass (BPSG), undoped silicate glass (USG), or the like. Other insulation materials formed by any acceptable process may be used. In some embodiments, a contact etch stop layer (CESL) **87** is disposed between the first ILD **88** and the epitaxial source/drain regions **82**, the masks **74**, and the gate spacers. The CESL **87** may comprise a dielectric material, such as, silicon nitride, silicon oxide, silicon oxynitride, or the like, having a different etch rate than the material of the overlying first ILD **88**.

[0048] In FIGS. **14A** and **14B**, a planarization process, such as a CMP, may be performed to level the top surface of the first ILD **88** with the top surfaces of the dummy gates **72** or the masks **74**. The planarization process may also remove the masks **74** on the dummy gates **72**, and portions of the first spacers **80** and the second spacers **86** along sidewalls of the masks **74**. After the planarization process, top surfaces of the dummy gates **72**, the first spacers **80**, the second spacers **86**, and the first ILD **88** are level. Accordingly, the top surfaces of the dummy gates **72** are exposed through the first ILD **88**. In some embodiments, the masks **74** may remain, in which case the planarization process levels the top surface of the first ILD **88** with the top surfaces of the masks **74**.

[0049] In FIGS. **15A** and **15B**, the dummy gates **72**, and the masks **74** if present, are removed in an etching step(s), so that recesses **90** are formed. Portions of the dummy dielectric layer **60** in the recesses **90** may also be removed. In some embodiments, only the dummy gates **72** are removed and the dummy dielectric layer **60** remains and is exposed by the recesses **90**. In some embodiments, the dummy dielectric layer **60** is removed from recesses **90** in a first region of a die (e.g., a core logic region) and remains in recesses **90** in a second region of the die (e.g., an input/output region). In some embodiments, the dummy gates **72** are removed by an anisotropic dry etch process. For example, the etching process may include a dry etch process using reaction gas(es) that selectively etch the dummy gates **72** without etching the first ILD **88** or the gate spacers. Each recess **90** exposes and/or overlies a channel region **58** of a respective fin **52**. Each channel region **58** is disposed between neighboring pairs of the epitaxial source/drain regions **82**. During the removal, the dummy dielectric layer **60** may be used as an etch stop layer when the dummy gates **72** are etched. The dummy dielectric layer **60** may then be optionally removed after the removal of the dummy gates **72**.

[0050] In FIGS. **16A** and **16B**, gate dielectric layers **92** and gate electrodes **94** are formed for replacement gates. FIG. **16C** illustrates a detailed view of region **89** of FIG. **16B**. Gate dielectric

layers **92** are deposited conformally in the recesses **90**, such as on the top surfaces and the sidewalls of the fins **52** and on sidewalls of the gate spacers. The gate dielectric layers **92** may also be formed on the top surface of the first ILD **88**. In accordance with some embodiments, the gate dielectric layers **92** comprise silicon oxide, silicon nitride, or multilayers thereof. In some embodiments, the gate dielectric layers **92** include a high-k dielectric material, and in these embodiments, the gate dielectric layers **92** may have a k value greater than about 7.0, and may include a metal oxide or a silicate of hafnium, aluminum, zirconium, lanthanum, manganese, barium, titanium, lead, and combinations thereof. The formation methods of the gate dielectric layers **92** may include Molecular-Beam Deposition (MBD), ALD, PECVD, and the like. In embodiments where portions of the dummy dielectric layer **60** remains in the recesses **90**, the gate dielectric layers **92** include a material of the dummy dielectric layer **60** (e.g., silicon oxide).

[0051] The gate electrodes **94** are deposited over the gate dielectric layers **92**, respectively, and fill the remaining portions of the recesses **90**. The gate electrodes **94** may include a metal-containing material such as titanium nitride, titanium oxide, tantalum nitride, tantalum carbide, cobalt, ruthenium, aluminum, tungsten, combinations thereof, or multi-layers thereof. For example, although a single layer gate electrode **94** is illustrated in FIG. **16B**, the gate electrode **94** may comprise any number of liner layers **94A**, any number of work function tuning layers **94B**, and a fill material **94C** as illustrated by FIG. **16C**. After the filling of the recesses **90**, a planarization process, such as a CMP, may be performed to remove the excess portions of the gate dielectric layers **92** and the material of the gate electrodes **94**, which excess portions are over the top surface of the ILD **88**. The remaining portions of material of the gate electrodes **94** and the gate dielectric layers **92** thus form replacement gates of the resulting FinFETs. The gate electrodes **94** and the gate dielectric layers **92** may be collectively referred to as a “gate stack.” The gate and the gate stacks may extend along sidewalls of a channel region **58** of the fins **52**.

[0052] The formation of the gate dielectric layers **92** in the region **50N** and the region **50P** may occur simultaneously such that the gate dielectric layers **92** in each region are formed from the same materials, and the formation of the gate electrodes **94** may occur simultaneously such that the gate electrodes **94** in each region are formed from the same materials. In some embodiments, the gate dielectric layers **92** in each region may be formed by distinct processes, such that the gate dielectric layers **92** may be different materials, and/or the gate electrodes **94** in each region may be formed by distinct processes, such that the gate electrodes **94** may be different materials. Various masking steps may be used to mask and expose appropriate regions when using distinct processes.

[0053] In FIGS. **17A** and **17B**, a second ILD **108** is deposited over the first ILD **88**. In some embodiment, the second ILD **108** is a flowable film formed by a flowable CVD method. In some embodiments, the second ILD **108** is formed of a dielectric material such as PSG, BSG, BPSG, USG, or the like, and may be deposited by any suitable method, such as CVD and PECVD. In accordance with some embodiments, before the formation of the second ILD **108**, the gate stack (including a gate dielectric layer **92** and a corresponding overlying gate electrode **94**) is recessed, so that a recess is formed directly over the gate stack and between opposing portions of second spacers **86**, as illustrated in FIGS. **17A** and **17B**. A gate mask **96** comprising one or more layers of dielectric material, such as silicon nitride, silicon oxynitride, or the like, is filled in the recess, followed by a planarization process to remove excess portions of the dielectric material extending over the first ILD **88**. The subsequently formed gate contacts **110** (see FIGS. **18A-B**) penetrate through the gate mask **96** to contact the top surface of the recessed gate electrode **94**.

[0054] In FIGS. **18A** and **18B**, gate contacts **110** and source/drain contacts **112** are formed through the second ILD **108** and the first ILD **88**, in accordance with some embodiments. Openings for the source/drain contacts **112** are formed through the first and second ILDs **88** and **108**, and openings for the gate contact **110** are formed through the second ILD **108** and the gate mask **96**. The openings may be formed using acceptable photolithography and etching techniques. A liner, such as a diffusion barrier layer, an adhesion layer, or the like, and a conductive material are formed in the

openings. The liner may include titanium, titanium nitride, tantalum, tantalum nitride, or the like. The conductive material may be copper, a copper alloy, silver, gold, tungsten, cobalt, aluminum, nickel, or the like. A planarization process, such as a CMP, may be performed to remove excess material from a surface of the ILD **108**. The remaining liner and conductive material form the source/drain contacts **112** and gate contacts **110** in the openings. An anneal process may be performed to form a silicide at the interface between the epitaxial source/drain regions **82** and the source/drain contacts **112**. The source/drain contacts **112** are physically and electrically coupled to the epitaxial source/drain regions **82**, and the gate contacts **110** are physically and electrically coupled to the gate electrodes **94**. The source/drain contacts **112** and gate contacts **110** may be formed in different processes, or may be formed in the same process. Although shown as being formed in the same cross-sections, it should be appreciated that each of the source/drain contacts **112** and gate contacts **110** may be formed in different cross-sections, which may avoid shorting of the contacts.

[0055] The disclosed FinFET embodiments could also be applied to nanostructure devices such as nanostructure (e.g., nanosheet, nanowire, gate-all-around, or the like) field effect transistors (NSFETs). In an NSFET embodiment, the fins are formed by patterning a stack of alternating layers of channel layers and sacrificial layers. The dummy gate stacks and epitaxial source/drain regions are formed in a similar manner as described above. After the dummy gate stacks are removed, the sacrificial layers can be partially or fully removed in the channel regions. The replacement gate structures are formed in a similar manner as described above and will partially or completely surround the channel layers in the channel region of the NSFET devices. The ILDs and contacts to the gate structures and source/drains are formed in a similar manner as described above. A nanostructure device can be formed as disclosed in U.S. Patent Application Publication 2016/0365414, which is incorporated herein by reference in its entirety.

[0056] The embodiments described herein may achieve advantages. The techniques described herein describe the formation of epitaxial source/drain regions having reduced volume and reduced cross-sectional area. For example, using the techniques described herein, the epitaxial material formed on adjacent fins may merge at a higher point, which reduces the overall cross-sectional area of the merged epitaxial source/drain region. The merge height and the cross-sectional area may be controlled according to the desired application by controlling the amount of a gate spacer material deposited between adjacent fins and by controlling the parameters of the etching process that forms gate spacers from the gate spacer material. By reducing the cross-sectional area of the epitaxial source/drain region, parasitic capacitances (e.g., gate-to-drain capacitance (C_{gd})) may be reduced, which can reduce RC delay, and allow for faster on/off switching and boosted device speed, such as the speed of a ring-oscillator (RO) device.

[0057] In accordance with some embodiments, a device includes a first fin and a second fin extending from a substrate, the first fin including a first recess and the second fin including a second recess; an isolation region surrounding the first fin and surrounding the second fin; a gate stack over the first fin and the second fin; a spacer material over the isolation region and surrounding the first fin and the second fin, wherein a first portion of the spacer material that extends from a first side of the first fin to the second fin has a first vertical thickness, wherein a second portion of the spacer material adjacent a second side of the first fin opposite the first side has a second vertical thickness that is less than the first vertical thickness; and a source/drain region in the first recess and in the second recess, the source/drain region adjacent the gate stack, wherein the source/drain region includes a first bottom surface extending over the first portion of the spacer material and a second bottom surface extending over the second portion of the spacer material, wherein a bottom of the second bottom surface is closer to the isolation region than a bottom of the first bottom surface. In an embodiment, the first bottom surface and the second bottom surface are faceted. In an embodiment, a top of the first bottom surface is farther from the isolation region than a top of the second bottom surface. In an embodiment, the top of the first bottom surface is in the

range between 5 nm and 70 nm from the isolation region. In an embodiment, the difference between the first vertical thickness and the second vertical thickness is in the range between 5 nm and 40 nm. In an embodiment, the source/drain region extends on a sidewall of the first portion of the spacer material. In an embodiment, a sidewall of the second portion of the spacer material that is adjacent the second side of the first fin is free of the source/drain region. In an embodiment, the spacer material includes a first layer of a first dielectric material and a second layer of a second dielectric material. In an embodiment, the first portion of the spacer material protrudes above a bottom surface of the first recess and a bottom surface of the second recess.

[0058] In accordance with some embodiments, a structure includes a first fin over a semiconductor substrate; a second fin over the semiconductor substrate, the second fin being adjacent the first fin; an isolation region surrounding the first fin and the second fin; a gate spacer material over the isolation region, wherein the gate spacer material between a first side of the first fin and a first side of the second fin extends farther above the isolation region than the gate spacer material on a second side of the first fin that is opposite the first side of the first fin, wherein the first side of the first fin and the first side of the second fin are facing each other; a gate structure along sidewalls and over upper surfaces of the first fin and the second fin; and a source/drain region on the first fin and the second fin adjacent the gate structure, the source/drain region including a downward-facing first facet on the first side of the first fin and a downward-facing second facet on the second side of the first fin, wherein a first portion of the source/drain region on the first side of the first fin extends on a sidewall of the gate spacer material and a second portion of the source/drain region on the second side of the first fin extends over a top surface of the gate spacer material, wherein the first portion and the second portion are the same height above the isolation region. In an embodiment, a bottom of the first facet is farther above the isolation region than a bottom of the second facet. In an embodiment, a top of the first facet is farther above the isolation region than a top of the second facet. In an embodiment, the second distance is zero. In an embodiment, a top surface of the source/drain region is flat. In an embodiment, the first facet and the second facet have a (111) crystalline orientation. In an embodiment, the structure includes a downward-facing third facet on the first side of the second fin, wherein the third facet terminates at the first facet.

[0059] In accordance with some embodiments, a method includes forming fins protruding from a semiconductor substrate; forming a gate structure over the fins; forming an isolation region surrounding the fins; depositing a spacer layer over the gate structure and over the fins, wherein the spacer layer fills the regions extending between pairs of adjacent fins; performing a first etching process on the spacer layer, wherein after performing the first etching process, first remaining portions of the spacer layer that are within inner regions extending between pairs of adjacent fins have a first thickness and second remaining portions of the spacer layer that are not within the inner regions have a second thickness that is less than the first thickness; and forming an epitaxial source/drain region adjacent the gate structure and extending over the fins, wherein portions of the epitaxial source/drain region within the inner regions are separated from the first remaining portions of the spacer layer. In an embodiment, the method includes forming a second etching process on the fins to form a recess within each respective fin. In an embodiment, the epitaxial source/drain region has a bottom surface that is closer to the isolation region than the second remaining portions of the spacer layer. In an embodiment, depositing the spacer layer includes depositing a first dielectric layer and then conformally depositing a second dielectric layer on the first dielectric layer.

[0060] The foregoing outlines features of several embodiments so that those skilled in the art may better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that

they may make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

Claims

1. A method of forming a semiconductor device, the method comprising: forming a first semiconductor structure and a second semiconductor structure extending from a substrate; forming an isolation region adjacent the first semiconductor structure and adjacent the second semiconductor structure; forming a dielectric structure over the isolation region and along sidewalls of the first semiconductor structure and the second semiconductor structure, wherein a first portion of the dielectric structure that extends from a first side of the first semiconductor structure to the second semiconductor structure has a first vertical thickness, wherein a second portion of the dielectric structure adjacent a second side of the first semiconductor structure opposite the first side has a second vertical thickness that is less than the first vertical thickness; recessing the first semiconductor structure and the second semiconductor structure to form a first recess in first semiconductor structure and a second recess in the second semiconductor structure, wherein the first recess exposes more of a sidewall of the first portion of the dielectric structure than the second portion of the dielectric structure; and forming an epitaxial region over the first recess and the second recess, wherein the epitaxial region comprises a first bottom surface extending over the first portion of the dielectric structure and a second bottom surface extending over the second portion of the dielectric structure, wherein a bottom of the second bottom surface is closer to the isolation region than a bottom of the first bottom surface.
2. The method of claim 1, wherein the epitaxial region comprises a first downward facing facet extending upward from the first recess and a second downward facing facet extending upward from the second recess, the first downward facing facet intersecting with the second downward facing facet at a merge point, the merge point being above an upper surface of the isolation region by a distance in a range of 5 nm to 70 nm.
3. The method of claim 2, wherein the first downward facing facet has a (111) crystal orientation.
4. The method of claim 1, wherein a distance between the bottom of the second bottom surface and the bottom of the first bottom surface is in a range of 5 nm and 40 nm.
5. The method of claim 1, wherein a distance between the bottom of the second bottom surface and an upper surface of the isolation region is in a range of 0 nm and 30 nm.
6. The method of claim 1, wherein a distance between the bottom of the first bottom surface and an upper surface of the isolation region is in a range of 5 nm and about 40 nm.
7. The method of claim 1, wherein the epitaxial region directly contacts a vertical sidewall of the dielectric structure.
8. A method of forming a semiconductor device, the method comprising: forming a first semiconductor structure and a second semiconductor structure extending from a substrate; forming an isolation region adjacent the first semiconductor structure and adjacent the second semiconductor structure; forming a dielectric structure over the isolation region and along sidewalls of the first semiconductor structure and the second semiconductor structure, wherein a first portion of the dielectric structure extends from a first side of the first semiconductor structure to the second semiconductor structure, wherein a second portion of the dielectric structure is adjacent a second side of the first semiconductor structure opposite the first side; recessing the first semiconductor structure and the second semiconductor structure to form a first recess in first semiconductor structure and a second recess in the second semiconductor structure, wherein the first recess exposes more of a sidewall of the first portion of the dielectric structure than the second portion of the dielectric structure; and forming an epitaxial region over the first recess and the second recess.
9. The method of claim 8, wherein the first portion has a greater vertical thickness than the second portion.

- 10.** The method of claim 8, wherein the epitaxial region comprises a first bottom surface extending over the first portion of the dielectric structure and a second bottom surface extending over the second portion of the dielectric structure, wherein a bottom of the second bottom surface is closer to the isolation region than a bottom of the first bottom surface.
 - 11.** The method of claim 8, wherein the first semiconductor structure is a first fin, wherein the second semiconductor structure is a second fin.
 - 12.** The method of claim 8, wherein a first surface of the epitaxial region extending from the first recess and a second surface of the epitaxial region extending from the second recess have a (111) crystal orientation.
 - 13.** The method of claim 12, wherein the first surface intersects the second surface.
 - 14.** The method of claim 8, further comprising: forming a gate stack over the first semiconductor structure and the second semiconductor structure, wherein the dielectric structure extends along sidewalls of the gate stack.
 - 15.** A method of forming a semiconductor device, the method comprising: forming a first fin over a substrate, the first fin comprising a first inner sidewall and a first outer sidewall; forming a second fin over the substrate, the second fin being adjacent the first fin, the first inner sidewall of the first fin facing a second inner sidewall of the second fin; forming a dielectric structure over the substrate and adjacent the first fin and the second fin, wherein a height of the dielectric structure along the first inner sidewall is greater than a height of the dielectric structure along the first outer sidewall, wherein forming the dielectric structure comprises: forming a first material layer; and forming a second material layer over the first material layer, wherein a thickness of the first material layer is about the same adjacent the first inner sidewall as adjacent the first outer sidewall, wherein a thickness of the second material layer adjacent the first inner sidewall is greater than adjacent the first outer sidewall; forming recesses in the first fin and the second fin; and forming an epitaxial source/drain region in the recesses in the first fin and the second fin, the epitaxial source/drain region comprising a semiconductor material different than a material of the first fin and the second fin, wherein the epitaxial source/drain region extends over the dielectric structure from the first outer sidewall at a first point lower than a second point where the epitaxial source/drain region extends over the dielectric structure from the first inner sidewall in a cross-sectional view.
 - 16.** The method of claim 15, wherein the dielectric structure has a uniform height between the first fin and the second fin.
 - 17.** The method of claim 15, wherein a minimum height of the dielectric structure between the first fin and the second fin is greater than a minimum height of the dielectric structure on a side of the first fin opposite the second fin.
 - 18.** The method of claim 15, further comprising forming an isolation region between the first fin and the second fin, wherein the dielectric structure is formed over the isolation region, wherein the epitaxial source/drain region from the first fin merges with the epitaxial source/drain region from the second fin at a height of 5 nm to 70 nm above the isolation region.
 - 19.** The method of claim 15, wherein after forming the recesses, a height of the first fin is less than a height of the second fin.
 - 20.** The method of claim 15, further comprising forming a gate structure over the first fin and the second fin, wherein the first material layer and the second material layer extends along sidewalls of the gate structure.
-